



## Material Content Data Sheet



<b>Sales Product Name</b>		BTT6020-1EKA		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001134408						
<b>Package</b>		PG-DSO-14-47		<b>Weight*</b>		150.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.172	2.11	2.11	21061	21061
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		459	
	non noble metal	iron	7439-89-6	1.383	0.92		9185	
wire	non noble metal	copper	7440-50-8	56.175	37.29	38.27	372933	382692
	non noble metal	copper	7440-50-8	0.713	0.47	0.47	4732	4732
	organic material	carbon black	1333-86-4	0.168	0.11		1118	
encapsulation	plastics	epoxy resin	-	7.746	5.14		51425	
	inorganic material	silicondioxide	60676-86-0	76.282	50.64	55.89	506421	558964
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16409	16409
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9761	9761
glue	plastics	epoxy resin	-	0.168	0.11		1117	
	noble metal	silver	7440-22-4	0.793	0.53	0.64	5264	6381
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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